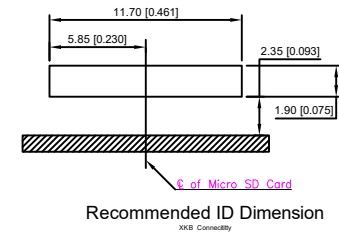
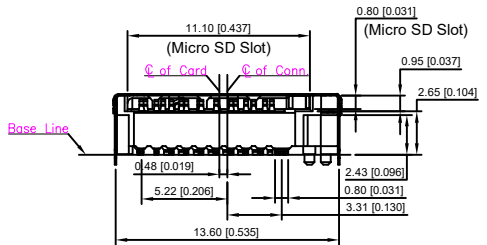
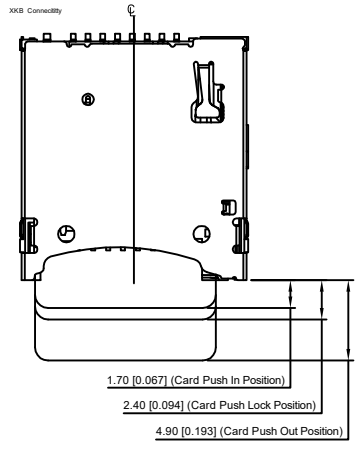
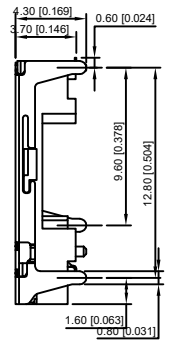
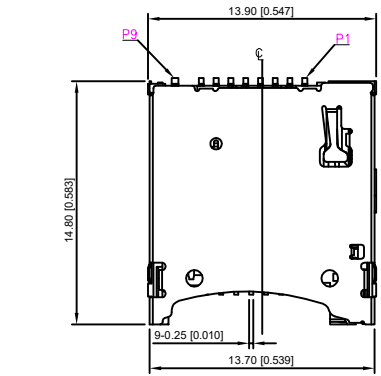


| Card Detect Switch | |
|---------------------|-------|
| Card Uninsertion | Open |
| Card Half Insertion | Open |
| Card Insertion | Close |
| Open | Close |



| Pin No. | Pin Assignment |
|---------|--------------------|
| P1 | Micro SD DAT2 |
| P2 | Micro SD CD/DAT3 |
| P3 | Micro SD CMD |
| P4 | Micro SD VDD1 |
| P5 | Micro SD CLK |
| P6 | Micro SD VSS |
| P7 | Micro SD DAT0/CLK+ |
| P8 | Micro SD DAT1/CLK- |
| P9 | Micro SD CD |
| P10 | GND |
| P11 | GND |
| P12 | GND |
| P13 | GND |
| P14 | GND |
| P15 | Micro SD VDD2 |
| P16 | Micro SD SWIO |
| P17 | Micro SD VSS |
| P18 | Micro SD D0+ |
| P19 | Micro SD D0- |
| P20 | Micro SD VSS |
| P21 | Micro SD D1- |
| P22 | Micro SD D1+ |
| P23 | Micro SD VSS |

- Note:
- 材料 Material
 - 1-1.塑料 Plastic:LCP, S470, Black, UL94V-0
 - 1-2.触点 Contact:C5210-H
 - 1-3.外壳 Shell:SUS304-H
 - 电镀 Plating:
 - 2-1.触点 Contact:
 - 接触电阻 Contact Area: Au 1u"min.Plating Over Ni 50u" min.
 - 焊尾 Solder tail: Gold Flash Plating Over Ni 50u" min.
 - 2-2. 外壳 Shell:
 - Solderability Ni 50u"min.Over All
 - Contact And Tail Coplanarity To Be 0.10mm max.



| REVISIONS | | | | | | ANGLAR | ±5° | DSND | DATE | SCALE: N/A | MODEL TYPE: | | |
|---|-------------|------|---------|----------|--|------------------------|------|--------------------------------------|------|-------------|--------------|-------|----------|
| Δx | | | | | | L ≤ 4 | ±0.2 | DWN | DATE | VIEW: | TF CARD CONN | | |
| Δx | | | | | | 4 < L ≤ 16 | ±0.3 | CHKD | DATE | UNIT: mm/in | PART NO.: | | |
| Δx | | | | | | 16 < L ≤ 63 | ±0.4 | APPD | DATE | SIZE: A4 | DWG NO.: | | |
| MARK | DESCRIPTION | DATE | REVISED | APPROVED | | L > 63 | ±0.5 | | | | XXTF-1150-11 | | |
| | | | | | | UNSPECIFIED TOLERANCES | | XKB INDUSTRIAL PRECISION CO.,LIMITED | | | WEIGHT | SHEET | REVISIOI |
| www.xk-dg.cn www.helloxkb.com www.helloxkb.cn | | | | | | | | | | | 1.0g | 1/1 | A0 |